

Product Summary

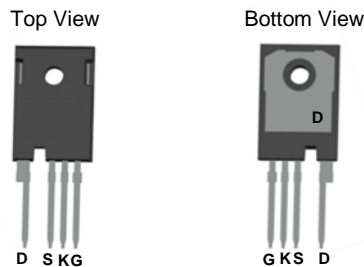
BV_{DSS}	$R_{DS(ON)}$ Max	I_D $T_C = +25^\circ C$
1200V	28.5m Ω @ $V_{GS} = 15V$	100A

Description and Applications

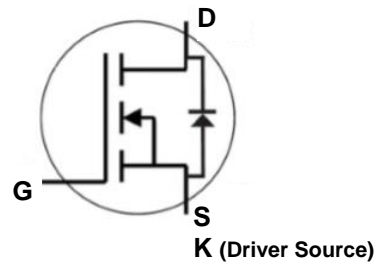
This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- EV high-power DC-DC converters
- EV charging systems
- AC-DC traction inverters
- Automotive motor drivers

TO247-4 (Type WH)



Pin Configuration



Internal Schematic

Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The DMWSH120H28SM4Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Package: TO247-4
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 **e3**
- Weight: 6.6 grams (Approximate)

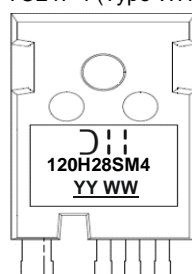
Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMWSH120H28SM4Q	TO247-4 (Type WH)	30 Pieces	Tube

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

TO247-4 (Type WH)



= Manufacturer's Marking
 120H28SM4 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 23 = 2023)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	1200	V
Gate-Source Voltage (Dynamic)	V _{GSS}	+19/-8	V
Gate-Source Voltage (Static)	V _{GSS}	+15/-4	V
Continuous Drain Current (Notes 5, 9)	I _D	T _C = +25°C	100
		T _C = +100°C	70.8
Continuous Diode Forward Current (Note 5)	I _S	87	A
Pulsed Source Current (10μs Pulse, Duty Cycle = 1%) (Note 5)	I _{SM}	430	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%) (Note 5)	I _{DM}	430	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	T _C = +25°C	429
		T _C = +100°C	214
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	28.8	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	0.35	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	1200	—	—	V	V _{GS} = 0V, I _D = 100μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	50	μA	V _{DS} = 1200V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±250	nA	V _{GS} = +15/-4V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	1.8	2.5	3.6	V	V _{DS} = V _{GS} , I _D = 17.7mA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	20	28.5	mΩ	V _{GS} = 15V, I _D = 50A
Diode Forward Voltage	V _{SD}	—	3.8	—	V	V _{GS} = -4V, I _S = 25A
Transconductance	g _{fs}	—	15	—	S	V _{DS} = 20V, I _D = 50A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	3944	—	pF	V _{GS} = 0V, V _{DS} = 1000V, V _{AC} = 25mV, f = 1MHz
Output Capacitance	C _{oss}	—	180	—		
Reverse Transfer Capacitance	C _{rss}	—	9.73	—		
C _{oss} Stored Energy	E _{oss}	—	114.6	—	μJ	
Turn-On Switching Energy (Body Diode Forward)	E _{ON}	—	744	—	μJ	V _{GS} = -4V/+15V, V _{DS} = 800V, R _g = 2.5Ω, I _D = 50A, L = 157μH
Turn-Off Switching Energy (Body Diode Forward)	E _{OFF}	—	1818	—		
Gate Resistance	R _g	—	1.3	—	Ω	V _{AC} = 25mV, f = 1MHz
Total Gate Charge	Q _g	—	156.3	—	nC	V _{GS} = -4V/+15V, V _{DS} = 800V, I _D = 50A
Gate-Source Charge	Q _{gs}	—	34.5	—		
Gate-Drain Charge	Q _{gd}	—	56.4	—		
Turn-On Delay Time	t _{d(ON)}	—	23.83	—	ns	V _{GS} = -4V/+15V, V _{DD} = 800V, R _g = 2.5Ω, L = 157μH
Turn-On Rise Time	t _r	—	59.66	—		
Turn-Off Delay Time	t _{d(OFF)}	—	48.00	—		
Turn-Off Fall Time	t _f	—	12.52	—		
Body Diode Reverse Recovery Time	t _{RR}	—	33.89	—	ns	V _{GS} = -4V, V _{DS} = 800V, I _D = 50A, di/dt = 2600A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	317.93	—		
Body Diode Reverse Recovery Current	I _{RRM}	—	18.76	—		

- Notes:
- Device mounted on an infinite heatsink.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Guaranteed by design. Not subject to production testing.
 - Short duration pulse test used to minimize self-heating effect.
 - Drain current limited by maximum junction temperature.

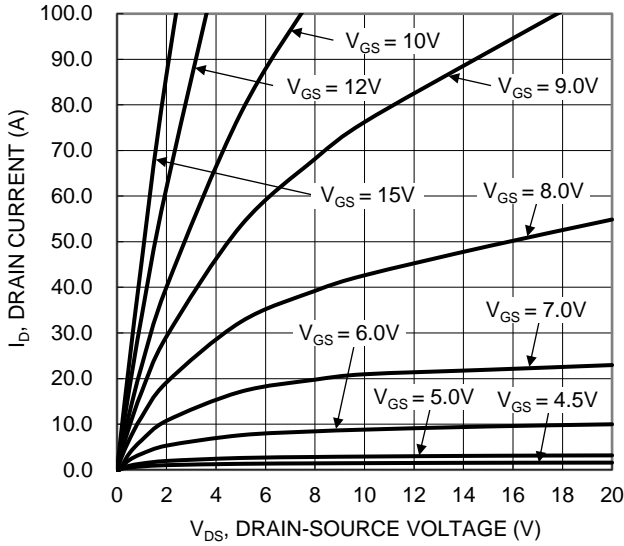


Figure 1. Typical Output Characteristic

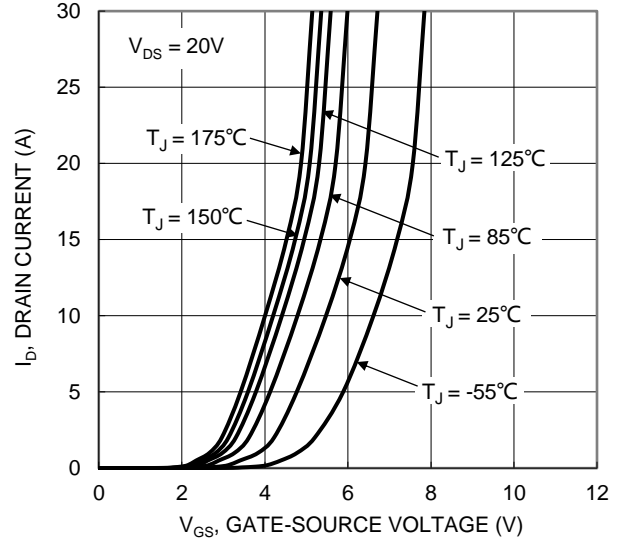


Figure 2. Typical Transfer Characteristic

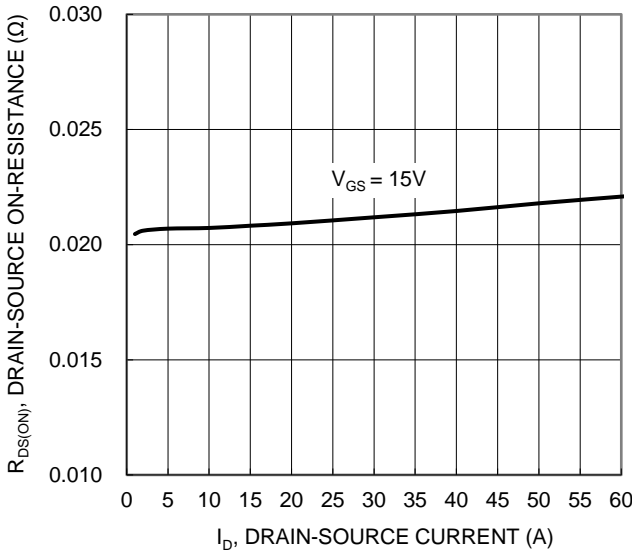


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

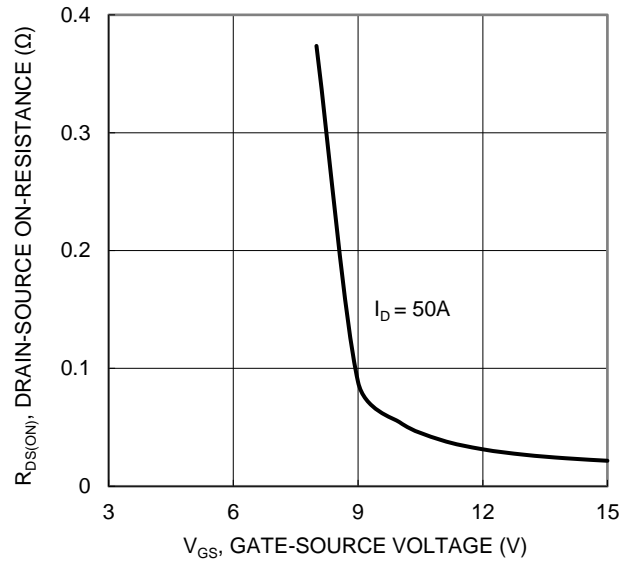


Figure 4. Typical Transfer Characteristic

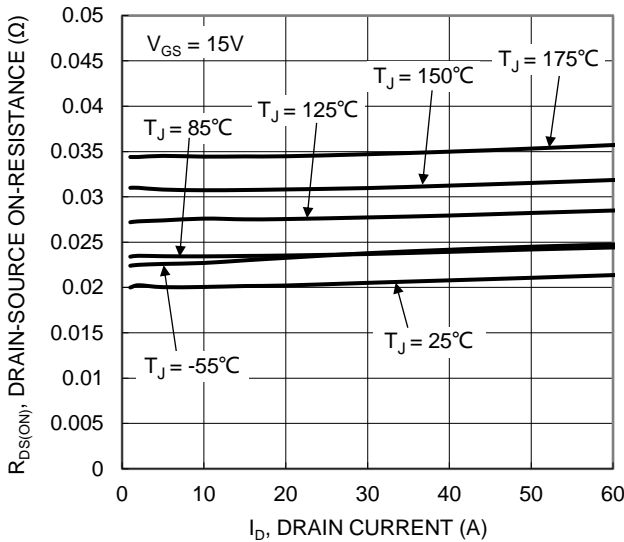


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

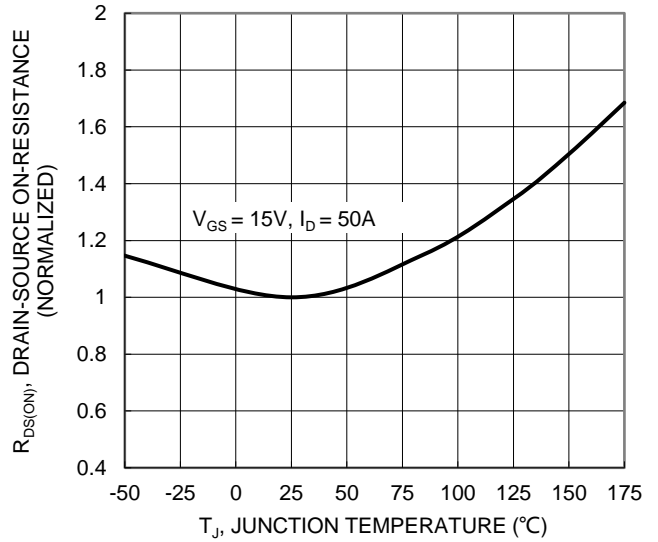


Figure 6. On-Resistance Variation with Temperature

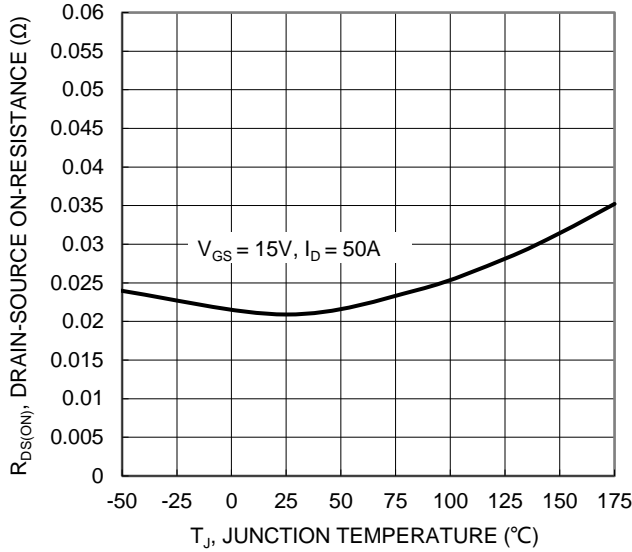


Figure 7. On-Resistance Variation with Temperature

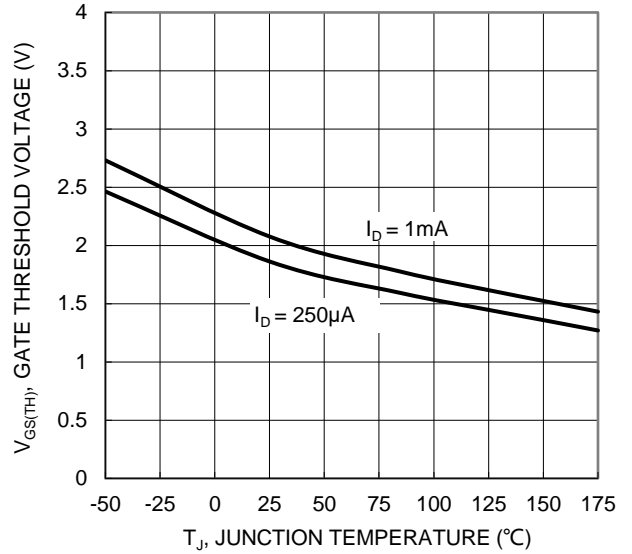


Figure 8. Gate Threshold Variation vs. Junction Temperature

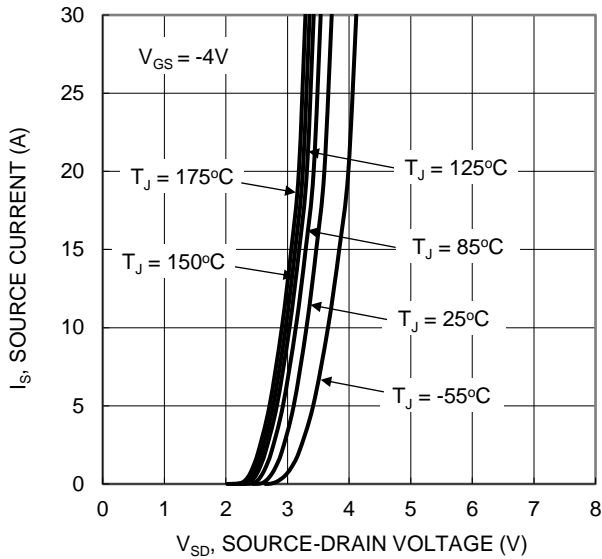


Figure 9. Diode Forward Voltage vs. Current

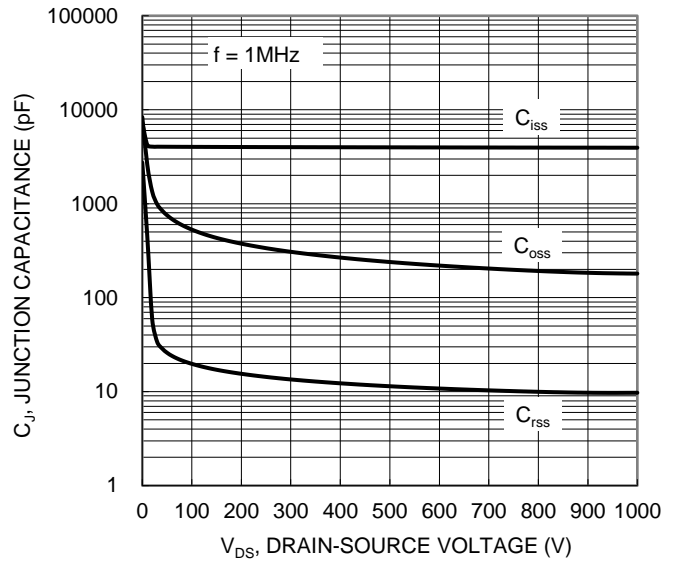


Figure 10. Typical Junction Capacitance

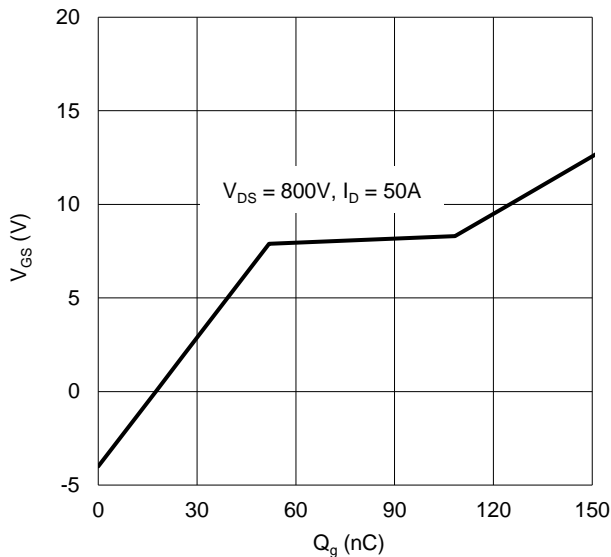


Figure 11. Gate Charge

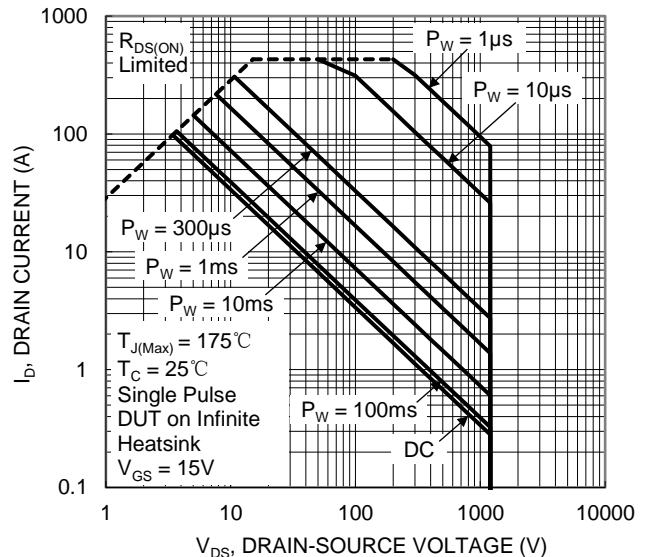


Figure 12. SOA, Safe Operation Area

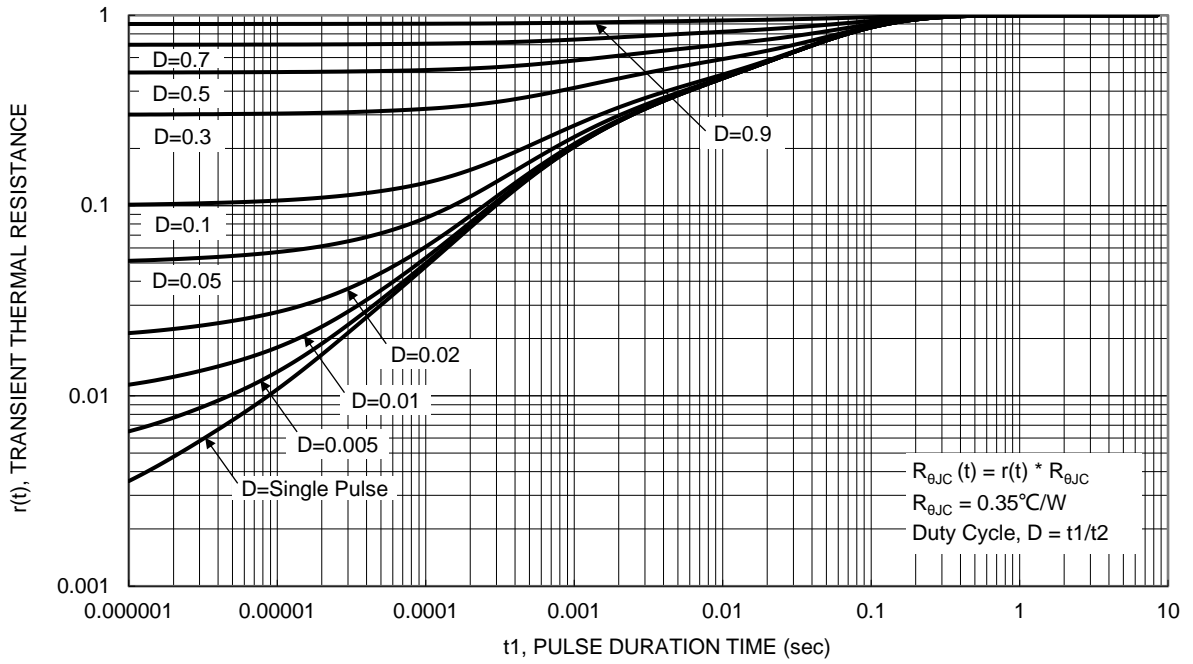
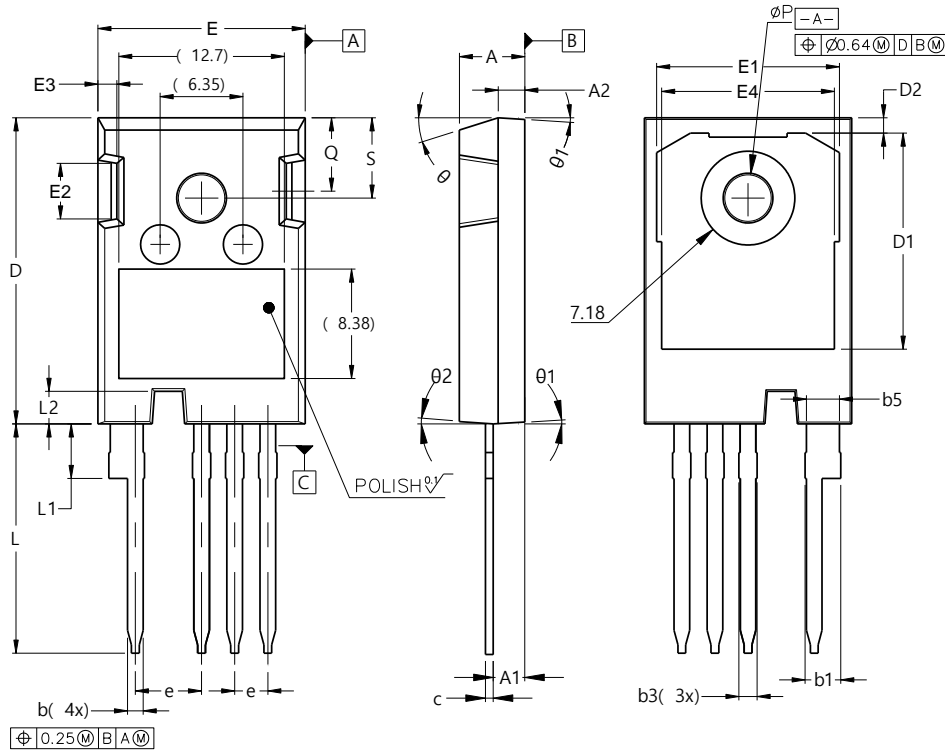


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO247-4 (Type WH)



TO247-4 (Type WH)		
Dim	Min	Max
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b	1.07	1.33
b1	2.39	2.94
b3	1.07	1.60
b5	2.39	2.69
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.30
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	2.54 BSC	
e1	5.08 BSC	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
ΦP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
θ	17.5° REF	
θ_1	3.5° REF	
θ_2	4° REF	
All Dimensions in mm		

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